

**What Is Claimed Is:**

1       1. A semiconductor device with improved electrostatic  
2 discharge (ESD) tolerance, comprising:

3            a pad on a semiconductor substrate of a first-conductive  
4            type;

5            a finger-type transistor on the semiconductor substrate,  
6            comprising:

7              at least one drain region of a second-conductive type,  
8              coupled to the pad;

9              a plurality of source regions of the second-conductive  
10             type, coupled to a power rail; and

11             a plurality of channel regions formed on the  
12             semiconductor substrate, each channel region  
13             located between one of the source regions and one  
14             of the at least one drain region;

15            a well stripe of the second-conductive type on the  
16            semiconductor substrate, extending in a first direction  
17            at an angle to a channel width direction of at least one  
18            of the channel regions; and

19            a doped segment of the first-conductive type in the well  
20            stripe, coupled to the pad.

21  
22       2. The semiconductor device as claimed in claim 1,  
23 wherein the angle is around 90°.

1       3. The semiconductor device as claimed in claim 1,  
2 wherein the well stripe is coupled to the pad.

1       4. The semiconductor device as claimed in claim 3,  
2 wherein the well has at least one contact region of the  
3 second-conductive type coupled to the pad.

1       5. The semiconductor device as claimed in claim 4,  
2 wherein the contact region is located between the doped segment  
3 and the finger-type transistor.

1       6. The semiconductor device as claimed in claim 4,  
2 wherein the doped segment is located between the contact region  
3 and the finger-type transistor.

1       7. The semiconductor device as claimed in claim 4,  
2 wherein the contact region is spaced apart from an end of the  
3 doped segment.

1       8. The semiconductor device as claimed in claim 1,  
2 wherein the doped segment is formed by a plurality of doped  
3 regions of the first conductivity type distributed in the well  
4 stripe.

1       9. The semiconductor device as claimed in claim 1,  
2 wherein the well stripe is located between the finger-type  
3 transistor and the pad.

1       10. The semiconductor device as claimed in claim 1,  
2 wherein the well stripe is located under the pad.

1       11. The semiconductor device as claimed in claim 1,  
2 wherein the finger-type transistor has gate fingers, each gate  
3 finger corresponding to one of the channel regions.

1       12. The semiconductor device as claimed in claim 11,  
2 wherein at least one of the gate fingers is coupled to the power  
3 rail.

1       13. The semiconductor device as claimed in claim 11,  
2 wherein at least one of the gate fingers is coupled to a gate  
3 signal line.

1       14. The semiconductor device as claimed in claim 1,  
2 wherein the finger-type transistor is a field-oxide transistor,  
3 the field-oxide transistor comprises a plurality of isolation  
4 segments, and each isolation segment overlaps one of the channel  
5 regions.

1       15. The semiconductor device as claimed in claim 1,  
2 wherein the semiconductor device further comprises a pickup ring  
3 of the first-conductive type on the semiconductor substrate, the  
4 pickup ring coupled to the power rail and extending around the  
5 finger-type transistor on three sides.

1       16. The semiconductor device as claimed in claim 15,  
2 wherein the pickup ring surrounds the finger-type transistor and  
3 the well stripe.

1       17. A pad Cell of a semiconductor integrated circuit,  
2 comprising:

3           a pad;  
4            a transistor formed on a substrate of a first conductive  
5       type;  
6            a conductor segment positioned between the pad and the  
7       transistor for coupling the pad and the transistor;  
8            a well region of a second conductive type formed in the  
9       substrate and spaced apart from the transistor; and  
10          a first doped region disposed in the well region;  
11          wherein  
12           the well region is positioned substantially under the  
13       conductor segment; and  
14           the first doped region is coupled to the conductor segment.

1           18. The cell as claimed in claim 17, wherein the first  
2       doped region is of the first conductive type.

1           19. The cell as claimed in claim 18, further comprising  
2       a second doped region of the second conductive type disposed in  
3       the well region and coupled to the conductor segment.

1           20. The cell as claimed in claim 19, wherein the first  
2       doped region is positioned substantially between the second  
3       doped region and the transistor.

1           21. The cell as claimed in claim 17, wherein the  
2       transistor is formed in an active region, the active region is  
3       substantially surrounded by an isolation region, and the well  
4       region is spaced apart from the active region by less than  
5       20.1um.

1           22. The cell as claimed in claim 21, wherein the well  
2 region is spaced apart from the active region by less than 5.1um.

1           23. The cell as claimed in claim 22, wherein the well  
2 region is spaced apart from the active region by less than 2.1um.